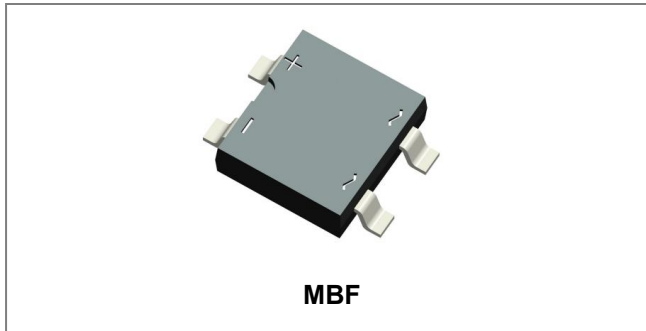


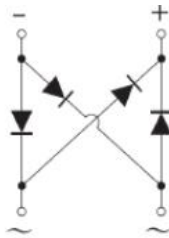
## MB05F THRU MB10F SINGLE PHASE 0.8AMP SURFACE MOUNT GLASS PASSIVATED BRIDGE RECTIFIER



### Features

- Glass passivated die construction
- Low forward voltage drop
- High current capability
- High surge current capability
- Designed for surface mount application
- Plastic material-UL flammability 94V-0
- This is a Pb – Free Device
- All SMC parts are traceable to the wafer lot
- Additional testing can be offered upon request

### Circuit Diagram



### Mechanical Data

- Case: MBF, Molded plastic
- Terminals: Plated leads solderable per MIL-STD-202, Method 208
- Polarity: as marked on case
- Mounting Position: Any
- Lead Free: For RoHS / Lead Free Version

### Maximum Ratings @ $T_A=25^{\circ}\text{C}$ unless otherwise specified

Type Number	Symbol	MB05F	MB1F	MB2F	MB4F	MB6F	MB8F	MB10F	Units
Peak Repetitive Reverse Voltage DC Blocking Voltage	$V_{RRM}$ $V_{DC}$	50	100	200	400	600	800	1000	V
RMS Voltage	$V_{RMS}$	35	70	140	280	420	480	700	V
Average Rectified Output Current (Note 1)@ $T_A=40^{\circ}\text{C}$ (Note 2)@ $T_A=40^{\circ}\text{C}$	$I_o$					0.5 0.8			A
Non-Repetitive Peak Forward Surge Current 8.3ms Single half sine-wave superimposed on rated load (JEDEC Method)	$I_{FSM}$					30			A

**Electrical Characteristics: @T<sub>A</sub>=25°C unless otherwise specified**

Type Number	Symbol	MB05F	MB1F	MB2F	MB4F	MB6F	MB8F	MB10F	Units
Forward Voltage per element @I <sub>F</sub> =0.8A	V <sub>FM</sub>				1.1				V
Peak Reverse Current @T <sub>A</sub> = 25°C At Rated DC Blocking Voltage @T <sub>A</sub> = 125°C	I <sub>R</sub>				5 500				μA
Typical Junction Capacitance (Note 3)	C <sub>j</sub>				13				pF

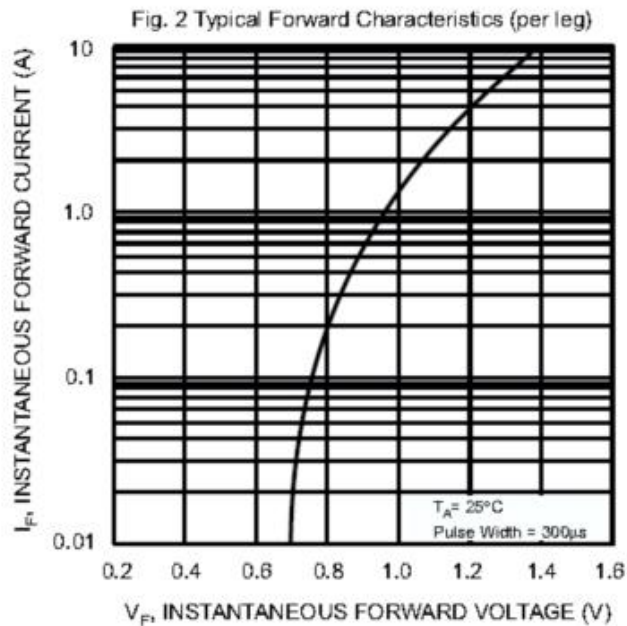
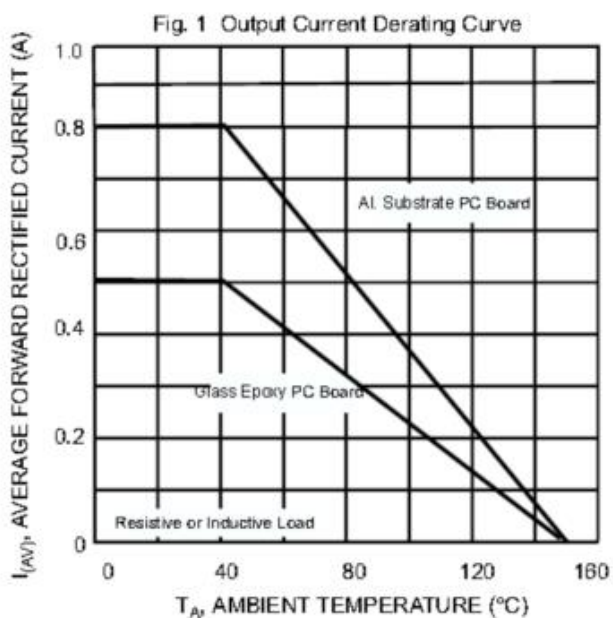
\* Pulse width < 300 μs, duty cycle < 2%

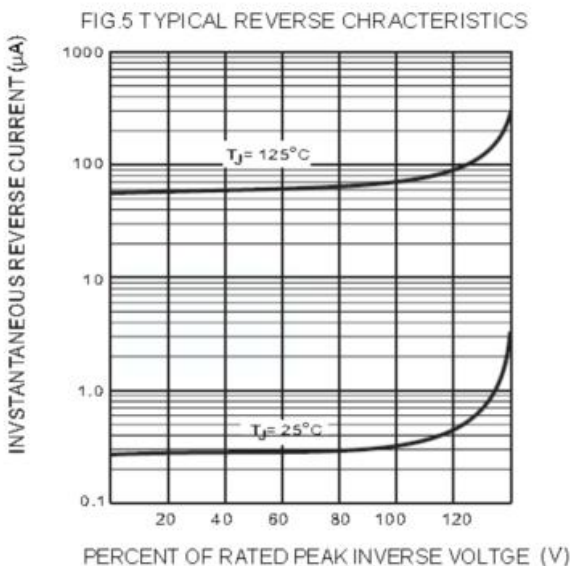
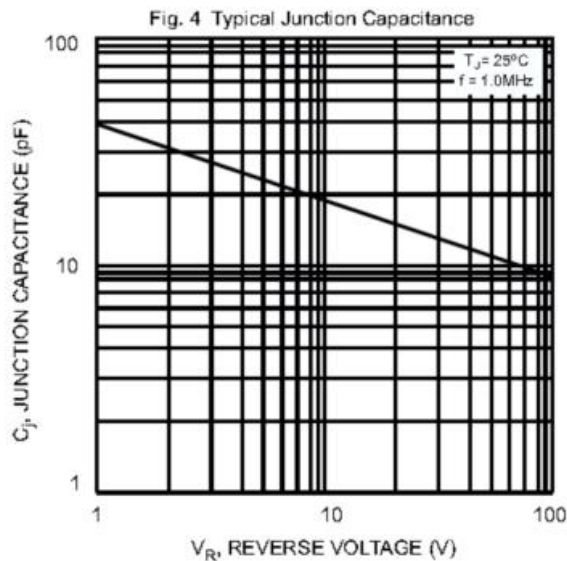
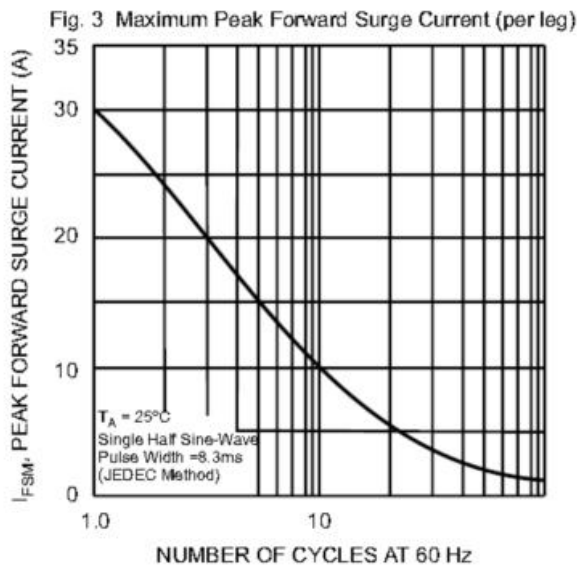
**Thermal-Mechanical Specifications: @T<sub>A</sub>=25°C unless otherwise specified**

Type Number	Symbol	MB05F	MB1F	MB2F	MB4F	MB6F	MB8F	MB10F	Units
Typical Thermal Resistance per leg	R <sub>θJA</sub>				60				°C/W
	R <sub>θJL</sub>				16				
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>				-55+150				°C

Note: 1. Mounted on glass epoxy PC board with 1.3mm<sup>2</sup> solder pad.  
2. Measured at 1.0 MHz and applied reverse voltage of 4.0V D.C.  
3. Thermal REsistance From Junction to Ambient

**Ratings and Characteristics Curves**



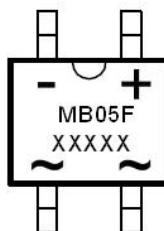


**Ordering Information**

Device	Package	Shipping
MB05F THRU MB10F	MBF (Pb-Free)	5000pcs / reel

For information on tape and reel specifications, including part orientation and tape sizes, please refer to our tape and reel packaging specification.

**Marking Diagram**

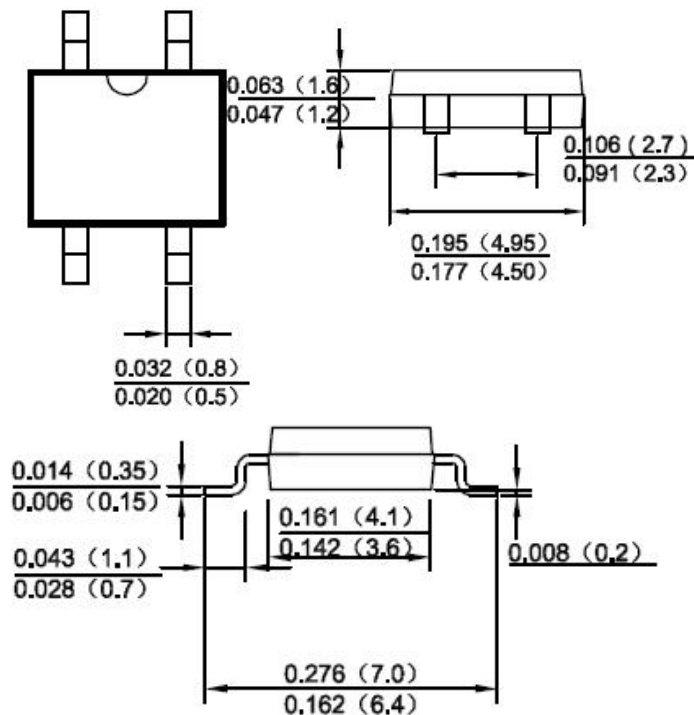


Where XXXXX is YYWWL

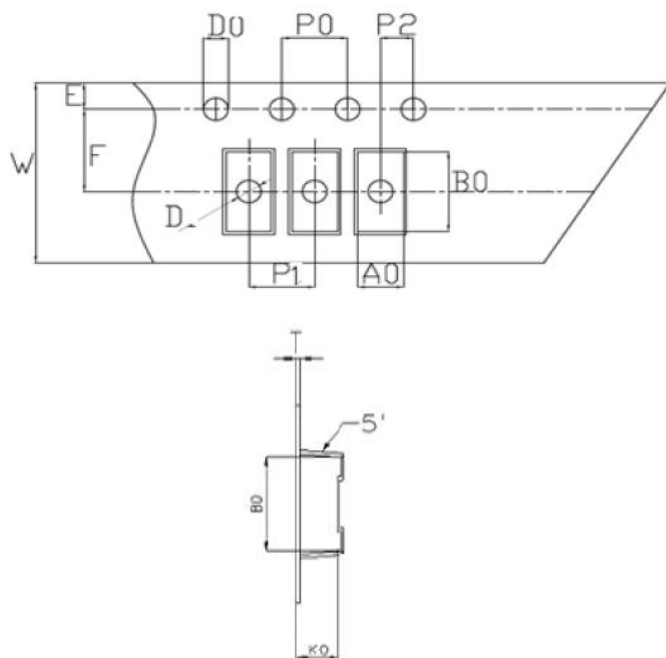
MB05F = Type Number  
YY = Year  
WW = Week  
L = Lot Number

**Cautions:** Molding resin  
Epoxy resin UL:94V-0

**Mechanical Dimensions MBF(Inches/Millimeters)**



**Carrier Tape & Reel Specification MBF**



SYMBOL	Millimeters	
	Min.	Max.
A0	5.21	5.41
B0	7.10	7.30
D0	1.50	1.60
D1	1.40	1.60
P0	3.90	4.10
P1	7.90	8.10
P2	1.95	2.05
E	1.65	1.85
K0	1.55	1.75
F	5.45	5.55
W	11.90	12.10
T	0.24	0.30
10P0	39.80	40.20

**Technical Data  
Data Sheet N1456, Rev. B**



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